

AUTOSWITCHING POWER MUX

Check for Samples: TPS2110A, TPS2111A

FEATURES

- Two-Input, One-Output Power Multiplexer with Low r_{DS(on)} Switches:
 - 84 mΩ Typ (TPS2111A)
 - 120 mΩ Typ (TPS2110A)
- Reverse and Cross-Conduction Blocking
- Wide Operating Voltage Range: 2.8 V to 5.5 V
- Low Standby Current: 0.5 μA Typ
 Low Operating Current: 55 μA Typ
- Adjustable Current Limit
- Controlled Output Voltage Transition Time: Limits Inrush Current Minimizes Output Voltage Hold-Up Capacitance
- CMOS- and TTL-Compatible Control Inputs
- Manual and Auto-Switching Operating Modes
- Thermal Shutdown
- Available in a TSSOP-8 Package

APPLICATIONS

- PCs
- PDAs
- Digital Cameras
- Modems
- Cell Phones
- Digital Radios
- MP3 Players

DESCRIPTION

The TPS211xA family of power multiplexers enables seamless transition between two power supplies, such as a battery and a wall adapter, each operating at 2.8 V to 5.5 V and delivering up to 1 A. The TPS211xA family includes extensive protection circuitry, including user-programmable current limiting, thermal protection, inrush current control, seamless supply transition, cross-conduction blocking, and reverse-conduction blocking. These features greatly simplify designing power multiplexer applications.

N1: 2.8 V to 5.5 V TPS2110A/TPS2111A 8 D₀ IN₁ 2 D₁ OUT 3 6 **VSNS** IN₂ ILIM **GND** IN2: 2.8 V to 5.5 V 勝 特 力 材 料 886-3-5753170 胜特力电子(上海) 86-21-34970699

TYPICAL APPLICATION

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This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

AVAILABLE OPTIONS

FEATURE Current Limit Adjustment Range		TPS2110A	TPS2111A	TPS2112A	TPS2113A	TPS2114A	TPS2115A
		0.31 A to 0.75 A	0.63 A to 1.25 A	0.31 A to 0.75 A	0.63 A to 1.25 A	0.31 A to 0.75 A	0.63 A to 1.25 A
Cuitabia a Madaa	Manual	Yes	Yes	No	No	Yes	Yes
Switching Modes	Automatic	Yes	Yes	Yes	Yes	Yes	Yes
Switch Status Output		No	No	Yes	Yes	Yes	Yes

ORDERING INFORMATION(1)

T _A	PACKAGE	ORDERING NUMBER	PACKAGE MARKING
-40°C to 85°C	TESOD 8 (DM)	TPS2110APW	2110A
-40°C to 85°C	TSSOP-8 (PW)	TPS2111APW	2111A

⁽¹⁾ For the most current package and ordering information see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.

ABSOLUTE MAXIMUM RATINGS(1)

Over recommended operating junction temperature range, unless otherwise noted.

		TPS2110A, TPS2111A	UNIT	
Input voltage range at pir	ns IN1, IN2, D0, D1, VSNS, ILIM ⁽²⁾	-0.3 to 6	V	
Output voltage range, V _C	(OUT) (2)	-0.3 to 6	V	
	TPS2110A	0.9		
Continuous output currer	TPS2111A	1.5	A	
Continuous total power d	issipation	See Dissipation Rat	ings table	
Operating virtual junction	temperature range, T _J	Internally Lim	ited	
Human body m	odel (HBM)	2	kV	
Charged device	e model (CDM)	500	V	

⁽¹⁾ Stresses beyond those listed under absolute maximum ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under recommended operating conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

DISSIPATION RATINGS

PACKAGE	DERATING FACTOR	T _A ≤ 25°C POWER	T _A = 70°C POWER	T _A = 85°C POWER
	ABOVE T _A = 25°C	RATING	RATING	RATING
TSSOP-8 (PW)	3.9 mW/°C	387 mW	213 mW	155 mW

Product Folder Link(s): TPS2110A TPS2111A

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⁽²⁾ All voltages are with respect to GND.

INSTRUMENTS

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RECOMMENDED OPERATING CONDITIONS

		TPS211	TPS2110A, TPS2111A		
		MIN	NOM MAX	UNIT	
Innertal voltage at INICV	V _{I(IN2)} ≥ 2.8 V	1.5	5.5	V	
nput voltage at IN1, V _{I(IN1)}	V _{I(IN2)} < 2.8 V	2.8	5.5	V	
Input voltage of INIQ V	V _{I(IN1)} ≥ 2.8 V	1.5	5.5	V	
Input voltage at IN2, V _{I(IN2)}	V _{I(IN1)} < 2.8 V	2.8	5.5	V	
Input voltage: V _{I(DO)} , V _{I(D1)} , V _{I(VSNS)}	ON. THE	0	5.5	V	
Current limit adjustment renge I	TPS2110A	0.31	0.75	Α	
Current limit adjustment range, $I_{O(OUT)}$	TPS2111A	0.63	1.25		
Operating virtual junction temperature, T _J		-40	125	°C	

ELECTRICAL CHARACTERISTICS: Power Switch

Over recommended operating junction temperature, $V_{I(IN1)} = V_{I(IN2)} = 5.5 \text{ V}$, and $R_{ILIM} = 400 \Omega$, unless otherwise noted.

				TI	PS2110A		TP	S2111A				
PARAMETER		TEST CONDITIONS		MIN	MIN TYP	MAX	MIN	TYP	MAX	UNIT		
			$V_{I(IN1)} = V_{I(IN2)} = 5.0 \text{ V}$		120	140		84	110	40		
	r _{DS(on)} ⁽¹⁾	$T_J = 25^{\circ}C$, $I_L = 500 \text{ mA}$	$V_{I(IN1)} = V_{I(IN2)} = 3.3 \text{ V}$		120	140		84	110	mΩ		
Drain-source on-state			$V_{I(IN1)} = V_{I(IN2)} = 2.8 \text{ V}$		120	140		84	110			
resistance (INx-OUT)		IDS(on)	T _J :		$V_{I(IN1)} = V_{I(IN2)} = 5.0 \text{ V}$	~ 1.	1	220			150	1
(IIX-OUT)				$T_J = 125$ °C, $I_L = 500 \text{ mA}$	$V_{I(IN1)} = V_{I(IN2)} = 3.3 \text{ V}$	~ ()		220	-1		150	mΩ
	1	16 = 000 1117	$V_{I(IN1)} = V_{I(IN2)} = 2.8 \text{ V}$			220			150			

The TPS211xA can switch a voltage as low as 1.5 V as long as there is a minimum of 2.8 V at one of the input power pins. In this specific case, the lower supply voltage has no effect on the IN1 and IN2 switch on-resistances.

ELECTRICAL CHARACTERISTICS

Over recommended operating junction temperature, $V_{I(IN1)} = V_{I(IN2)} = 5.5 \text{ V}$, $I_{O(OUT)} = 0 \text{ A}$, and $R_{ILIM} = 400 \Omega$, unless otherwise

100	21/1/2/100	TPS2110	OA, TPS2111A		-1
PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
LOGIC INPUTS (D0 AND D1)	4N 1 10 21 Co				
High-level input voltage V _{IH}	100,00	2			V
Low-level input voltage V _{IL}			-1	0.7	٧
Land aumont of DO and	D0 or D1 = High, sink current	0/2		1	
input current at Do or D1	D0 or D1 = Low, source current	0.5	1.4	5	μА
SUPPLY AND LEAKAGE CURR	ENTS	(O)			
1, 100 x COM	D1 = High, D0 = Low (IN1 active), $V_{I(IN2)} = 3.3 \text{ V}$	COM	55	90	
Supply current from IN1 (operation	D1 = High, D0 = Low (IN1 active), $V_{I(IN1)} = 3.3 \text{ V}$	4.00	1	12	μΑ
	$D0 = D1 = Low (IN2 active), V_{I(IN2)} = 3.3 V$			75	
Tupply current at D0 or D1 Supply AND LEAKAGE CURRENT Supply current from IN1 (operating) Supply current from IN2 (operating)	D0 = D1 = Low (IN2 active), V _{I(IN1)} = 3.3 V	100		1	
1007	D1 = High, D0 = Low (IN1 active), $V_{I(IN2)} = 3.3 \text{ V}$	1007	·03/	1	
Supply current from IN2 (operating	D1 = High, D0 = Low (IN1 active), $V_{I(IN1)} = 3.3 \text{ V}$	1007	COM	75	μА
	$D0 = D1 = Low (IN2 active), V_{I(IN2)} = 3.3 V$	/ 1		12	
	$D0 = D1 = Low (IN2 active), V_{I(IN1)} = 3.3 V$	1100	55	90	

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ELECTRICAL CHARACTERISTICS (continued)

Over recommended operating junction temperature, $V_{I(IN1)} = V_{I(IN2)} = 5.5 \text{ V}$, $I_{O(OUT)} = 0 \text{ A}$, and $R_{ILIM} = 400 \Omega$, unless otherwise noted

		W. Will	TPS21	10A, TPS211	1A	
PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
SUPPLY AND LEAKAGE	CURRENTS, con	ntinued			41	
Oliver of the State of the Stat		D0 = D1 = High (inactive), $V_{I(IN2)} = 3.3 \text{ V}$		0.5	2	
Quiescent current from IN1	(standby)	D0 = D1 = High (inactive), V _{I(IN1)} = 3.3 V			1	μА
0 : 11	4 4 41 3	D0 = D1 = High (inactive), $V_{I(IN2)} = 3.3 \text{ V}$	1100	1	1	
Quiescent current from IN2	(standby)	D0 = D1 = High (inactive), V _{I(IN1)} = 3.3 V		0.5	2	μΑ
Forward leakage current from (measured from OUT to GN		D0 = D1 = High (inactive), IN2 open, V _{O(OUT)} = 0 V (shorted), T _J = 25°C	M.J.	0.1	5	μА
Forward leakage current from (measured from OUT to GN		D0 = D1 = High (inactive), IN1 open, $V_{O(OUT)}$ = 0 V (shorted), T_J = 25°C		0.1	5	μА
Reverse leakage current to from INx to GND)	INx (measured	D0 = D1 = High (inactive), $V_{I(INx)} = 0 \text{ V}$, $V_{O(OUT)} = 5.5 \text{ V}$, $T_J = 25^{\circ}\text{C}$		0.3	5	μА
CURRENT LIMIT CIRCUIT	111	1		1100	-1 C	<i>y</i> ,
	TD004404	$R_{ILIM} = 400 \Omega$	0.51	0.63	0.80	
Current limit agains	TPS2110A	R _{ILIM} = 700 Ω	0.30	0.36	0.50	Α
Current limit accuracy	TDC0444A	$R_{ILIM} = 400 \Omega$	0.95	1.25	1.56	
	TPS2111A	$R_{ILIM} = 700 \Omega$	0.47	0.71	0.99	A
Current limit settling time	t _d	Time for short-circuit output current to settle within 10% of its steady state value.		1	1.100	ms
Input current at ILIM		$V_{I(ILIM)} = 0 \text{ V}, I_{O(OUT)} = 0 \text{ A}$	-15		0	μА
VSNS COMPARATOR		TIM. ON THE			W.	
VSNS threshold voltage		V _{I(VSNS)} ↑	0.78	0.80	0.82	100
		V _{I(VSNS)} ↓	0.735	0.755	0.775	V
VSNS comparator hysteres	is		30		60	mV
Deglitch of VSNS comparat	or (both ↑↓)	$\uparrow\downarrow)$		150	220	μS
Input current	.1	0 V ≤ V _{I(VSNS)} ≤ 5.5 V	- 1	•	1	μΑ
UVLO		100, 00,				1
INIA and INIQ LIV/LO		Falling edge	1.15	1.25		M
IN1 and IN2 UVLO		Rising edge		1.30	1.35	V
IN1 and IN2 UVLO hysteres	sis	1. 11. 01.	30	57	65	mV
Internal V _{DD} UVLO		Falling edge	2.4	2.53		V
(the higher of IN1 and IN2)		Rising edge		2.58	2.8	V
Internal V _{DD} UVLO hysteres	sis	11 21 2	30	50	75	mV
UVLO deglitch for IN1, IN2		Falling edge	90/	110		μS
REVERSE CONDUCTION	BLOCKING	N TW. I			(1	
Minimum output-to-input voltage difference to block switching	$\Delta V_{O(I_block)}$	D0 = D1 = high, $V_{I(INx)}$ = 3.3 V. Connect OUT to a 5-V supply through a series 1-k Ω resistor. Let D0 = low. Slowly decrease the supply voltage until OUT connects to IN1.	80	100	120	mV
THERMAL SHUTDOWN			. 007.			
Thermal shutdown threshol	d	TPS211xA is in current limit.	135	0		°C
Recovery from thermal shu	tdown	TPS211xA is in current limit.	125	40)		°C
Hysteresis			N.Y	10		°C
IN2-IN1 COMPARATORS	100	O. In	1100	700	1	
Hysteresis of IN2-IN1 comp	parator		0.1		0.2	V
Deglitch of IN2-IN1 compa	rator (both ↑ 1)		10	20	50	μS

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SWITCHING CHARACTERISTICS

Over recommended operating junction temperature, $V_{I(IN1)} = V_{I(IN2)} = 5.5 \text{ V}$, and $R_{ILIM} = 400 \Omega$, unless otherwise noted.

	100	CO2 4	(((11)	TF	PS2110A	ILIVI	TI	PS2111A	N	
P.	ARAMETER	TEST CO	NDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	UNIT
t _R	Output rise time from an enable	$V_{I(IN1)} = V_{I(IN2)} = 5 \text{ V}$	$T_J = 25^{\circ}C$, $C_L = 1 \mu F$, $I_L = 500 \text{ mA}$; see Figure 1(a).	0.5	1.0	1.5	1.7	1.8	3	ms
t _F	Output fall time from a disable	$V_{I(IN1)} = V_{I(IN2)} = 5 \text{ V}$	$T_J = 25^{\circ}C,$ $C_L = 1 \mu F,$ $I_L = 500 \text{ mA}; \text{ see}$ Figure 1(a).	0.35	0.5	0.7	0.5	CO	2	ms
		IN1 to IN2 transition, $V_{I(IN1)} = 3.3 \text{ V},$ $V_{I(IN2)} = 5 \text{ V}$	$T_J = 125^{\circ}C,$ $C_L = 10 \ \mu F,$ $I_L = 500 \ mA;$	N	40	60	1.100	40	60	77
t _T Tra	Transition time	IN2 to IN1 transition, $V_{I(IN1)} = 5 \text{ V}$, $V_{I(IN2)} = 3.3 \text{ V}$	measure transition time as 10% to 90% rise time or from 3.4 V to 4.8 V on V _{O(OUT)} . See Figure 1(b).		40	60		40	60	μs
t _{PLH1}	Turn-on propagation delay from an enable	$V_{I(IN1)} = VI_{(IN2)} = 5 \text{ V}$ Measured from enable to 10% of $V_{O(OUT)}$	$T_J = 25^{\circ}C$, $C_L = 10 \mu F$, $I_L = 500 \text{ mA}$; see Figure 1(a).	N. TY	0.5		NAM	10	01.0	ms
t _{PHL1}	Turn-off propagation delay from a disable	$V_{I(IN1)} = VI_{(IN2)} = 5 \text{ V}$ Measured from disable to 90% of $V_{O(OUT)}$	$T_J = 25^{\circ}\text{C},$ $C_L = 10 \ \mu\text{F},$ $I_L = 500 \ \text{mA}; \text{ see}$ Figure 1(a).	OMI	3		W	5	100	ms
t _{PLH2}	Switch-over rising propagation delay	$\begin{aligned} &\text{Logic 1 to Logic 0} \\ &\text{transition on D1,} \\ &V_{\text{I(IN1)}} = 1.5 \text{ V,} \\ &V_{\text{I(IN2)}} = 5 \text{ V,} \\ &V_{\text{I(DD)}} = 0 \text{ V,} \\ &\text{Measured from D1 to} \\ &10\% \text{ of } V_{\text{O(OUT)}} \end{aligned}$	$T_J = 25^{\circ}\text{C},$ $C_L = 10 \mu\text{F},$ $I_L = 500 \text{mA}; \text{see}$ Figure 1(c).	Y.COM	40	100		40	100	μs
t _{PHL2}	Switch-over falling propagation delay	Logic 0 to Logic 1 transition on D1, $V_{I(N1)} = 1.5 \text{ V}, \\ V_{I(N2)} = 5 \text{ V}, \\ V_{I(N2)} = 5 \text{ V}, \\ V_{I(N2)} = 0 \text{ V}, \\ \text{Measured from D1 to} \\ 90\% \text{ of } V_{O(OUT)}$	$T_J = 25^{\circ}\text{C},$ $C_L = 10 \mu\text{F},$ $I_L = 500 \text{mA}; \text{see}$ Figure 1(c).	2		10	2	5	10	ms

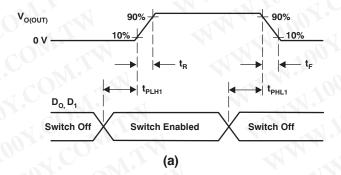
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PARAMETER MEASUREMENT INFORMATION

TIMING WAVEFORMS





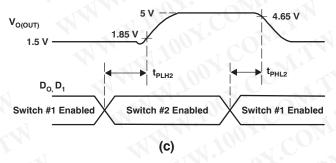


Figure 1. Propagation Delays and Transition Timing Waveforms



DEVICE INFORMATION

TRUTH TABLE

D1	D0	V _{I(VSNS)} > 0.8 V ⁽¹⁾	$V_{I(IN2)} > V_{I(IN1)}$	OUT ⁽²⁾
0	0	X	X CON	IN2
0	1	Yes	X	IN1
0	1 (No	No	IN1
0	1	No	Yes	IN2
1	0	X	X	IN1
1	1	X	X	Hi-Z

- (1) X = Don't care.
- (2) The undervoltage lockout circuit causes the output to go Hi-Z if the selected power supply does not exceed the IN1/IN2 UVLO, or if neither of the supplies exceeds the internal V_{DD} UVLO.

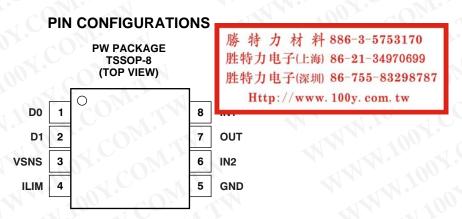
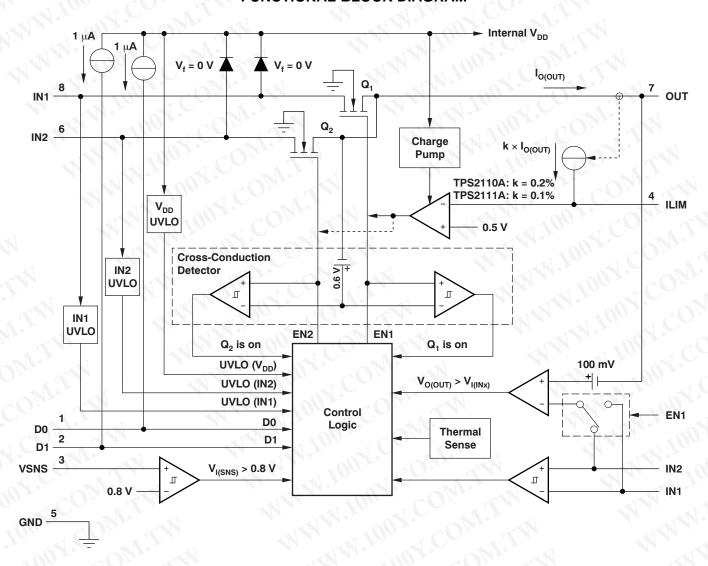


Table 1. TERMINAL FUNCTIONS

TERMINAL			
NAME	NO.	1/0	DESCRIPTION
D0	1	I	TTL- and CMOS-compatible input pins. Each pin has a 1-µA pull-up. The Truth Table
D1	2	, I	illustrates the functionality of D0 and D1.
GND	5	Power	Ground
IN1	8	NI I	Primary power switch input. The IN1 switch can be enabled only if the IN1 supply is above the UVLO threshold and at least one supply exceeds the internal V_{DD} UVLO.
IN2	6	I	Secondary power switch input. The IN2 switch can be enabled only if the IN2 supply is above the UVLO threshold and at least one supply exceeds the internal V _{DD} UVLO.
ILIM	4	1	A resistor ($R_{\rm ILIM}$) from ILIM to GND sets the current limit I _L to 250/ $R_{\rm ILIM}$ and 500/ $R_{\rm ILIM}$ for the TPS2110A and TPS2111A, respectively.
OUT	7	0	Power switch output
VSNS	3 . C		In the auto-switching mode (D0 = 1, D1 = 0), an internal power FET connects OUT to IN1 if the VSNS voltage is greater than 0.8 V. Otherwise, the FET connects OUT to the higher of IN1 and IN2. The Truth Table illustrates the functionality of VSNS.

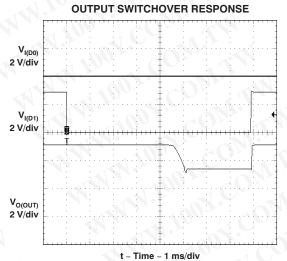


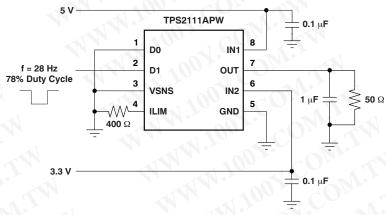
FUNCTIONAL BLOCK DIAGRAM





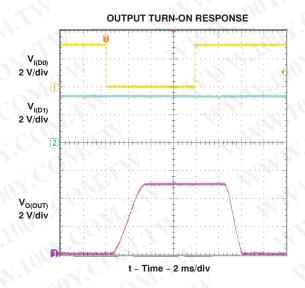
TYPICAL CHARACTERISTICS

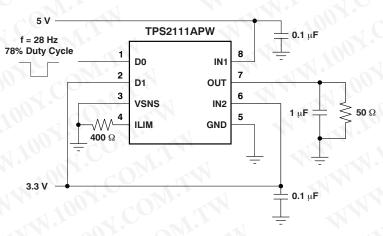




Output Switchover Response Test Circuit

Figure 2.





Output Turn-On Response Test Circuit

Figure 3.

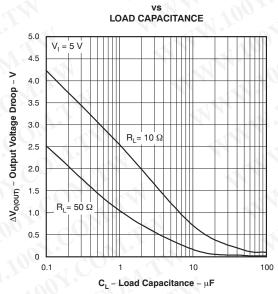


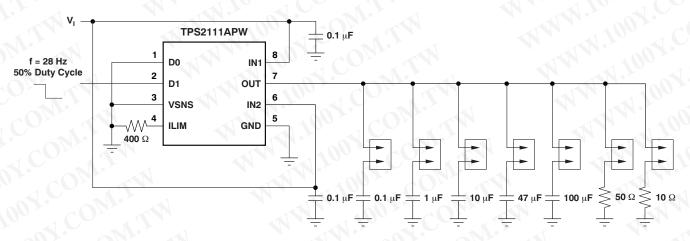
OUTPUT SWITCHOVER VOLTAGE DROOP TPS2111APW **0.1** μF $V_{I(D0)}$ 2 V/div 8 f = 580 Hz IN1 D0 90% Duty Cycle 2 7 D1 OUT $V_{I(D1)}$ 3 6 $C_L = 1 \mu F$ VSNS IN2 2 V/div \geq 50 Ω C_{L} ILIM GND V_{O(OUT)} 2 V/div = **0.1** μF $C_L = 0 \mu F$ **Output Switchover Voltage Droop Test Circuit** t - Time - 40 μs/div

Figure 4.



OUTPUT SWITCHOVER VOLTAGE DROOP

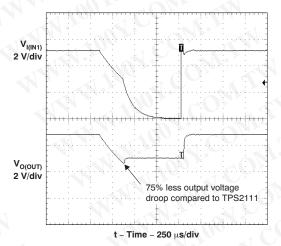


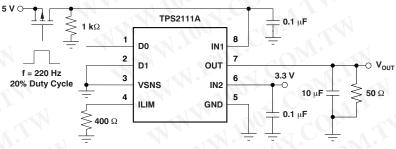


Output Switchover Voltage Droop Test Circuit Figure 5.



AUTO SWITCHOVER VOLTAGE DROOP

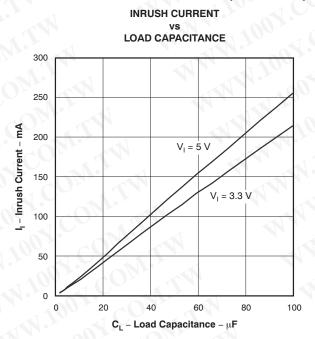


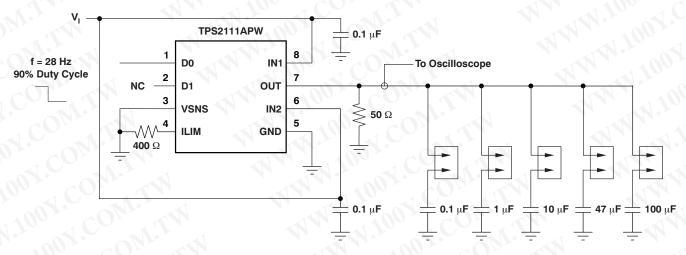


Auto Switchover Voltage Droop Test Circuit

Figure 6.

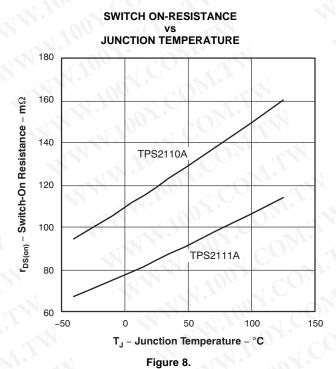




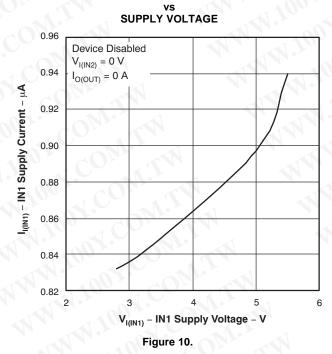


Output Capacitor Inrush Current Test Circuit Figure 7.

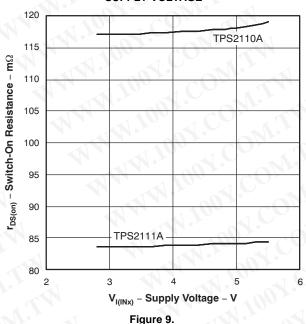




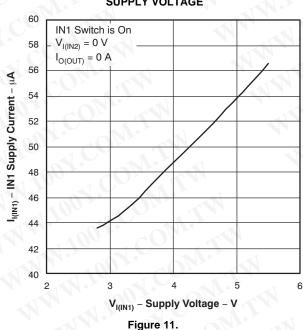
IN1 SUPPLY CURRENT



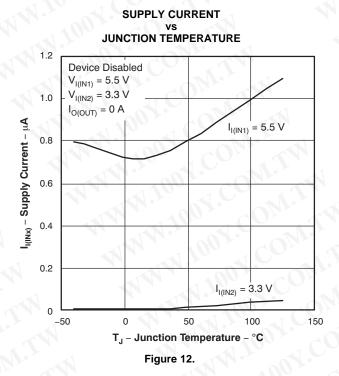
SWITCH ON-RESISTANCE vs SUPPLY VOLTAGE



IN1 SUPPLY CURRENT vs SUPPLY VOLTAGE







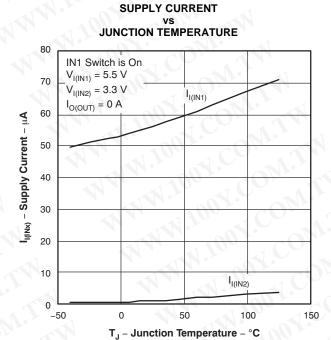


Figure 13.

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APPLICATION INFORMATION

Some applications have two energy sources, one of which should be used in preference to another. Figure 14 shows a circuit that will connect IN1 to OUT until the voltage at IN1 falls below a user-specified value. Once the voltage on IN1 falls below this value, the TPS211xA will select the higher of the two supplies. This usually means that the TPS211xA will swap to IN2.

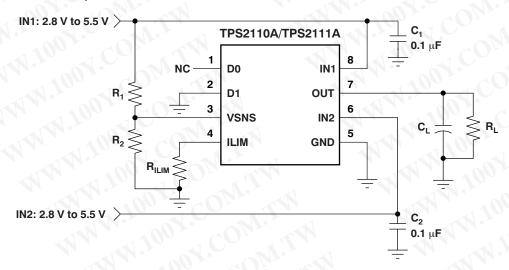


Figure 14. Auto-Selecting for a Dual Power-Supply Application

In Figure 15, the multiplexer selects between two power supplies based upon the EN1 logic signal. OUT connects to IN1 if EN1 is logic '1'; otherwise, OUT connects to IN2. The logic thresholds for the D1 terminal are compatible with both TTL and CMOS logic.

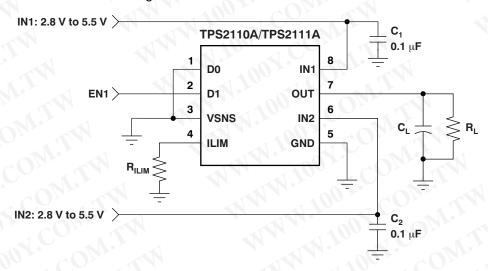


Figure 15. Manually Switching Power Sources

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DETAILED DESCRIPTION

AUTO-SWITCHING MODE

D0 equal to logic '1' and D1 equal to logic '0' selects the auto-switching mode. In this mode, OUT connects to IN1 if $V_{I(VSNS)}$ is greater than 0.8 V; otherwise, OUT connects to the higher of IN1 and IN2.

The VSNS terminal includes hysteresis equal to 3.75% to 7.5% of the threshold selected for transition from the primary supply to the higher of the two supplies. This hysteresis helps avoid repeated switching from one supply to the other due to resistive drops.

MANUAL SWITCHING MODE

D0 equal to logic '0' selects the manual-switching mode. In this mode, OUT connects to IN1 if D1 is equal to logic '1'; otherwise, OUT connects to IN2.

N-CHANNEL MOSFETs

Two internal high-side power MOSFETs implement a single-pole double-throw (SPDT) switch. Digital logic selects the IN1 switch, IN2 switch, or no switch (Hi-Z state). The MOSFETs have no parallel diodes so output-to-input current cannot flow when the FET is off. An integrated comparator prevents turn-on of a FET switch if the output voltage is greater than the input voltage.

CROSS-CONDUCTION BLOCKING

The switching circuitry ensures that both power switches will never conduct at the same time. A comparator monitors the gate-to-source voltage of each power FET and allows a FET to turn on only if the gate-to-source voltage of the other FET is below the turn-on threshold voltage.

REVERSE-CONDUCTION BLOCKING

When the TPS211xA switches from a higher-voltage supply to a lower-voltage supply, current can potentially flow back from the load capacitor into the lower-voltage supply. To minimize such reverse conduction, the TPS211xA will not connect a supply to the output until the output voltage has fallen to within 100 mV of the supply voltage. Once a supply has been connected to the output, it will remain connected regardless of output voltage.

CHARGE PUMP

The higher of supplies IN1 and IN2 powers the internal charge pump. The charge pump provides power to the current limit amplifier and allows the output FET gate voltage to be higher than the IN1 and IN2 supply voltages. A gate voltage that is higher than the source voltage is necessary to turn on the N-channel FET.

CURRENT LIMITING

A resistor R_{ILIM} from ILIM to GND sets the current limit to 250/ R_{ILIM} and 500/ R_{ILIM} for the TPS2110A and TPS2111A, respectively. Setting resistor R_{ILIM} equal to zero is not recommended as that disables current limiting.

OUTPUT VOLTAGE SLEW-RATE CONTROL

The TPS211xA slews the output voltage at a slow rate when OUT switches to IN1 or IN2 from the Hi-Z state (see the Truth Table). A slow slew rate limits the inrush current into the load capacitor. High inrush currents can glitch the voltage bus and cause a system to hang up or reset. It can also cause reliability issues—like pit the connector power contacts, when hot-plugging a load such as a PCI card. The TPS211xA slews the output voltage at a much faster rate when OUT switches between IN1 and IN2. The fast rate minimizes the output voltage droop and reduces the output voltage hold-up capacitance requirement.



REVISION HISTORY

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

CI	nanges from Original (March, 2004) to Revision A	Page
	Updated document to current format	1
•	Deleted package information from Available Options table	2
•	Revised Ordering Information table	2
•	Deleted <i>lead temperature</i> and <i>storage temperature</i> specifications from, added <i>electrostatic discharge</i> specifications to Absolute Maximum Ratings table; changed <i>operating virtual junction temperature</i> specification; deleted <i>ESD Protection</i> table	2
•	Updated conditions for Electrical Characteristics	3
•	Deleted footnote 1 for Electrical Characteristics table	3
•	Deleted footnote 1 for Switching Characteristics table	5

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PACKAGE OPTION ADDENDUM

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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins P	ackage Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
TPS2110APW	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS2110APWG4	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS2110APWR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS2110APWRG4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS2111APW	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS2111APWG4	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS2111APWR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS2111APWRG4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

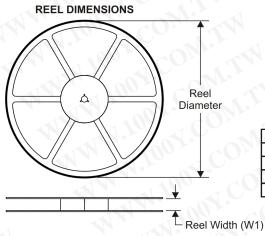
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PACKAGE MATERIALS INFORMATION

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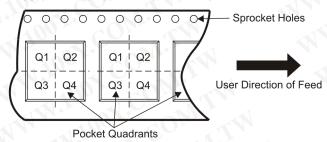
TAPE AND REEL INFORMATION



TAPE DIMENSIONS $\phi \phi \phi \phi \phi$ Cavity → A0 **←**

	A0	Dimension designed to accommodate the component width
1	B0	Dimension designed to accommodate the component length
	K0	Dimension designed to accommodate the component thickness
	W	Overall width of the carrier tape
y	P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



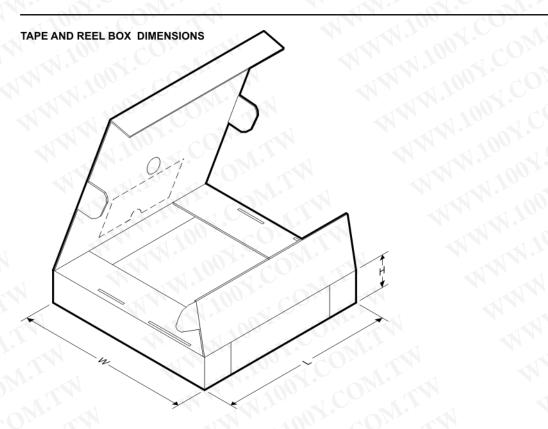
*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS2110APWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
TPS2111APWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1

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*All dimensions are nominal

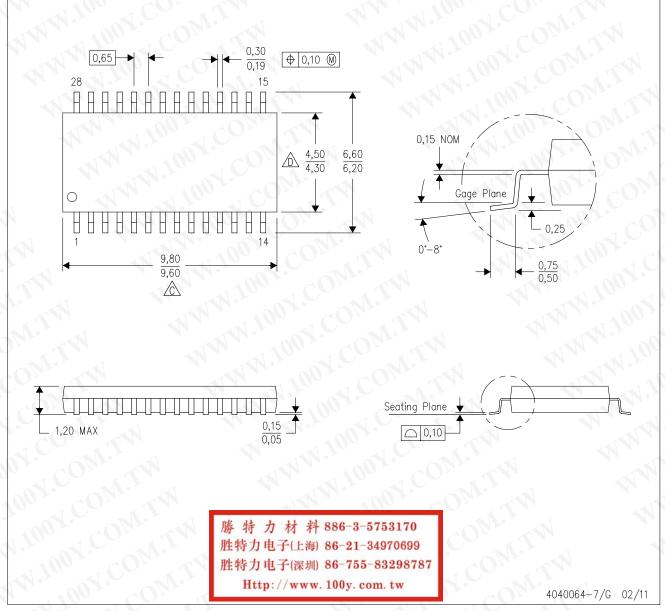
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dimensions are nominal Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm
	4.2		21 \				
TPS2110APWR	TSSOP	PW	8	2000	346.0	346.0	29.0
TPS2111APWR	TSSOP	PW	8	2000	346.0	346.0	29.0

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PW (R-PDSO-G28)

PLASTIC SMALL OUTLINE



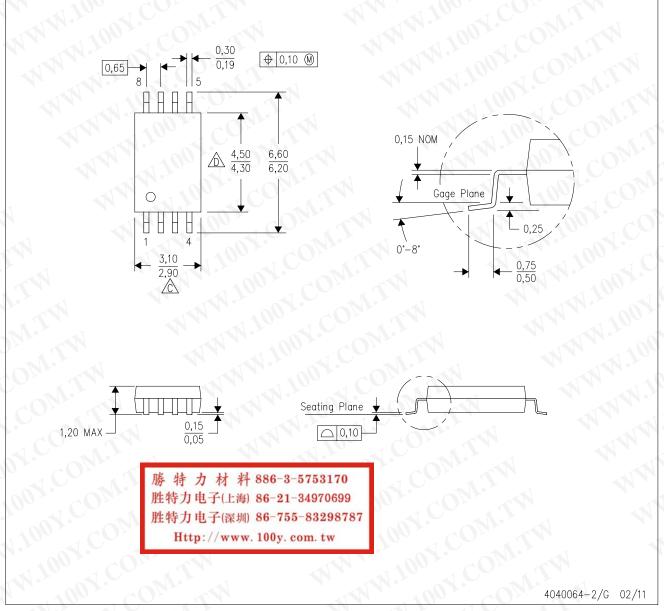
NOTES:

- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



PW (R-PDSO-G8)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
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- F. Falls within JEDEC MO-153



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